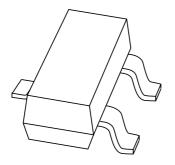
# DISCRETE SEMICONDUCTORS

# DATA SHEET



# **BAS17**Low-voltage stabistor

Product data sheet Supersedes data of 1999 May 31 2003 Mar 25



**NXP Semiconductors Product data sheet** 

# Low-voltage stabistor

**BAS17** 

#### **FEATURES**

• Low-voltage stabilization

• Forward voltage range: 580 to 960 mV

• Total power dissipation: max. 250 mW.

#### **APPLICATIONS**

• Low-voltage stabilization e.g.

- Bias stabilizer in class-B output stages

- Clipping

- Clamping

- Meter protection.

#### **DESCRIPTION**

Low-voltage stabilization diode in a small SOT23 plastic package.

#### **MARKING**

TYPE NUMBER	MARKING CODE(1)
BAS17	*A9

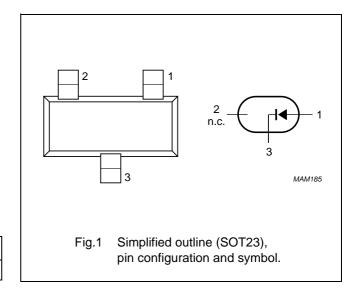
#### Note

1. \* = p: Made in Hong Kong. \* = t : Made in Malaysia.

\* = W : Made in China.

**PINNING** 

PIN	DESCRIPTION			
1	anode			
2	not connected			
3	cathode			



#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>R</sub>	continuous reverse voltage		_	5	V
I <sub>F</sub>	continuous forward current		_	200	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C	_	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C

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# Low-voltage stabistor

BAS17

#### **ELECTRICAL CHARACTERISTICS**

 $T_j = 25$  °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>F</sub>	forward voltage	see Fig.2				
		$I_F = 0.1 \text{ mA}$	580	_	660	mV
		I <sub>F</sub> = 1 mA	665	_	745	mV
		$I_F = 5 \text{ mA}$	725	_	805	mV
		I <sub>F</sub> = 10 mA	750	_	830	mV
		I <sub>F</sub> = 100 mA	870	_	960	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 4 V	_	_	5	μΑ
r <sub>dif</sub>	differential resistance	$I_F = 0.5 \text{ mA}$	_	120	_	Ω
		I <sub>F</sub> = 2 mA	_	80	_	Ω
S <sub>F</sub>	temperature coefficient	I <sub>F</sub> = 1 mA	_	-1.8	_	mV/K
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 0 V; f = 1 MHz	_	_	140	pF

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-tp</sub>	thermal resistance from junction to tie-point		330	K/W
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	500	K/W

#### Note

1. Device mounted on a FR4 printed-circuit board.

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# Low-voltage stabistor

BAS17

#### **GRAPHICAL DATA**

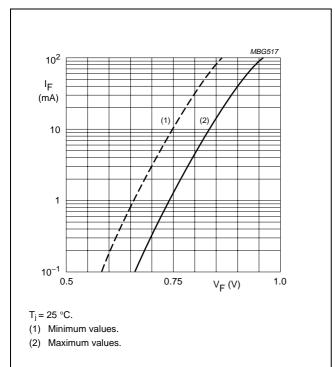


Fig.2 Forward current as a function of forward voltage

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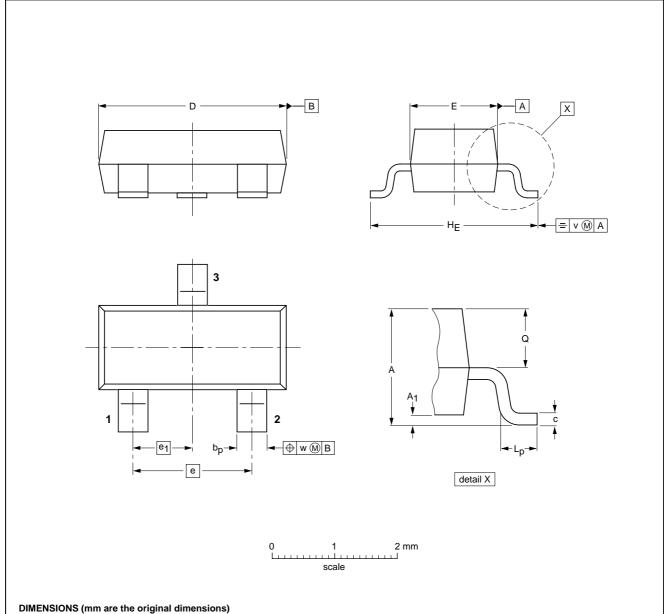
# Low-voltage stabistor

BAS17

#### **PACKAGE OUTLINE**

Plastic surface mounted package; 3 leads

SOT23



DIMENSIONS (mm are	the original	dimensions)
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UN	IT	A	A <sub>1</sub> max.	bp	C	D	E	е	e <sub>1</sub>	HE	L <sub>p</sub>	Q	٧	w
mı	n	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC EIAJ PROJECTION		ISSUE DATE		
SOT23		TO-236AB				<del>-97-02-28</del> 99-09-13

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### Low-voltage stabistor

**BAS17** 

#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### **Notes**

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#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors. No changes were made to the content, except for the legal definitions and disclaimers.

#### **Contact information**

For additional information please visit: http://www.nxp.com

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